

Title (en)

GALVANIZING SOLUTION FOR THE GALVANIC DEPOSITION OF COPPER

Title (de)

GALVANISIERUNGSLÖSUNG FÜR DIE GALVANISCHE ABSCHIEDUNG VON KUPFER

Title (fr)

SOLUTION DE GALVANISATION POUR LE DEPOT GALVANIQUE DE CUIVRE

Publication

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Application

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Abstract (en)

[origin: US6858123B1] The invention relates to a novel galvanizing solution for the galvanic deposition of copper. Hydroxylamine sulfate or hydroxylamine hydrochloride are utilized as addition reagents and added to the galvanizing solution during the galvanic deposition of copper which is used in the manufacture of semiconductors.

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IPC 8 full level

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